# CH \$165.00 155670

## TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 ETAS ID: TM502949

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

#### **CONVEYING PARTY DATA**

Name	Formerly	Execution Date	Entity Type
RAPID ENGINEERING LLC		12/19/2018	Limited Liability Company: DELAWARE

#### **RECEIVING PARTY DATA**

Name:	CIBC Bank USA	
Street Address:	dress: 120 South LaSalle Street	
City:	Chicago	
State/Country: ILLINOIS		
Postal Code: 60603		
Entity Type: banking corporation: ILLINOIS		

#### **PROPERTY NUMBERS Total: 6**

Property Type	Number	Word Mark
Registration Number:	1556700	RAPID
Registration Number:	2023219	
Registration Number:	2045777	RAPID
Registration Number:	2054607	RAPID
Registration Number:	1519713	BANANZA
Registration Number:	1919529	SPRAY-CURE

#### **CORRESPONDENCE DATA**

**Fax Number:** 3124607000

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 312-460-5000

Email: slott@seyfarth.com

Correspondent Name: Stephen D. Lott

Address Line 1: 233 S. Wacker Drive

Address Line 2: Suite 8000

Address Line 4: Chicago, ILLINOIS 60606

ATTORNEY DOCKET NUMBER:	058550-000092
NAME OF SUBMITTER:	Stephen D. Lott
SIGNATURE:	/Stephen D. Lott/

DATE SIGNED:	12/20/2018
Total Attachments: 7	
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#### PATENT AND TRADEMARK SECURITY AGREEMENT

THIS PATENT AND TRADEMARK SECURITY AGREEMENT (this "Agreement"), dated as of December 19, 2018, is made by RAPID ENGINEERING LLC, a Delaware limited liability company (the "Company"), in favor of CIBC Bank USA, in its capacity as administrative agent for the benefit of the financial institutions (the "Lenders") that are parties to the Credit Agreement referenced below from time to time (in such capacity, the "Administrative Agent"). All capitalized terms used in this Agreement and not otherwise defined shall have the same meanings as in the Credit Agreement referenced below.

#### **RECITALS**

- A. The Company and certain of its Affiliates have entered into a Credit Agreement dated as of the date hereof (as amended, restated, supplemented or otherwise modified from time to time, the "Credit Agreement") with the Lenders and the Administrative Agent, pursuant to which such Lenders have agreed to make loans to, and issue or participate in letters of credit for the account of, the Company and certain of its Affiliates.
- B. The Company and certain of its Affiliates have entered into a Guaranty and Collateral Agreement dated as of the date hereof (as amended, restated, supplemented or otherwise modified from time to time, the "Guaranty and Collateral Agreement") with the Administrative Agent pursuant to which certain obligations owed to the Lenders are secured.
- C. Pursuant to the Guaranty and Collateral Agreement, the Company is required to execute and deliver to the Administrative Agent, for the ratable benefits of the Lenders, this Agreement.
- D. Pursuant to the terms of the Guaranty and Collateral Agreement, the Company has granted to the Administrative Agent, for the ratable benefits of the Lenders, a security interest in substantially all the assets of the Company, including all right, title and interest of the Company in, to and under all now owned and hereafter acquired patents, patent applications, patent licenses, trademarks, trademark applications and trademark licenses, and all products and proceeds thereof, to secure the payment of all amounts owing by the Company and its Affiliates under the Credit Agreement and the Guaranty and Collateral Agreement.

In consideration of the mutual agreements set forth herein and in the Credit Agreement, the Company does hereby grant to the Administrative Agent, for the benefit of the Lenders, a continuing security interest in all of the Company's right, title and interest in, to and under the following, whether presently existing or hereafter created or acquired:

(1) each trademark and trademark application, including, without limitation, each trademark and trademark application referred to in <u>Schedule 1</u> annexed hereto, together with any reissues, continuations or extensions thereof and all goodwill associated therewith;

- (2) each trademark license, including, without limitation, each trademark license listed on <u>Schedule 1</u> annexed hereto, together with all goodwill associated therewith;
- (3) all products and proceeds of the foregoing, including, without limitation, any claim by the Company against third parties for past, present or future infringement of any trademark, including, without limitation, any trademark referred to in <u>Schedule 1</u> annexed hereto, any trademark issued pursuant to a trademark application referred to in <u>Schedule 1</u> and any trademark licensed under any trademark license listed on <u>Schedule 1</u> annexed hereto (items 1 through 3 being herein collectively referred to as the "<u>Trademark Collateral</u>");
- (4) each patent and patent application, including, without limitation, each patent and patent application referred to in <u>Schedule 2</u> annexed hereto, together with any reissues, continuations or extensions thereof and all goodwill associated therewith;
- (5) each patent license, including, without limitation, each patent license listed on Schedule 2 annexed hereto, together with all goodwill associated therewith; and
- (6) all products and proceeds of the foregoing, including, without limitation, any claim by the Company against third parties for past, present or future infringement of any patent, including, without limitation, any patent referred to in <a href="Schedule 2">Schedule 2</a> annexed hereto, any patent issued pursuant to a patent application referred to in <a href="Schedule 2">Schedule 2</a> and any patent licensed under any patent license listed on <a href="Schedule 2">Schedule 2</a> annexed hereto (items 4 through 6 being herein collectively referred to as the "<a href="Patent Collateral">Patent Collateral</a>").

This security interest is granted in conjunction with the security interests granted to the Administrative Agent pursuant to the Guaranty and Collateral Agreement and subject to limitations set forth therein. The Company hereby acknowledges and affirms that the rights and remedies of the Administrative Agent with respect to the security interest in the Trademark Collateral and the Patent Collateral made and granted hereby are more fully set forth in the Credit Agreement and Guaranty and Collateral Agreement, the terms and provisions of which are incorporated by reference herein as if fully set forth herein.

[signature page follows]

The Company has caused this Patent and Trademark Security Agreement to be duly executed by its duly authorized officer as of the date first set forth above.

#### RAPID ENGINEERING LLC

	By:  Aaron J. VanGetson  Vice President and Assistant Secretary
Acknowledged:	
CIBC BANK USA, as Administrative Agent	
By:Olga Krasner Managing Director	·····

[Signature Page to Patent and Trademark Security Agreement]

The Company has caused this Patent and Trademark Security Agreement to be duly executed by its duly authorized officer as of the date first set forth above.

#### RAPID ENGINEERING LLC

By:	
3,	Aaron J. VanGetson
	Vice President and Assistant Secretary

Acknowledged:

CIBC BANK USA, as Administrative Agent

Olga Krasner

Managing Director

[Signature Page to Patent and Trademark Security Agreement]

# SCHEDULE 1

to

## PATENT AND TRADEMARK SECURITY AGREEMENT

<u>U.S. Patent Registrations</u>
N/A
U.S. Patent Applications
N/A
Non-U.S. Patent Registrations N/A
Non-U.S. Patent Applications
N/A

## SCHEDULE 2

to

## PATENT AND TRADEMARK SECURITY AGREEMENT

## U.S. Trademark Registrations

Country	Serial No.	Registration No.	Application/ Registration Date	<u>Mark</u>	Current Assignee / Remarks
US	73691399	1556700	10/23/1987 09/19/1989	RAPID  THE DUIL	RAPID ENGINEERING LLC
US	74696978	2023219	07/03/1995 12/17/1996	O	RAPID ENGINEERING LLC
US	75059543	2045777	02/20/1996 12/24/1996	<b>Rapid</b>	RAPID ENGINEERING LLC
US	75060083	2054607	02/20/1996 04/22/1997	Rapid	RAPID ENGINEERING LLC
US	73691402	1519713	10/23/1987 01/10/1989	BANANZA	RAPID ENGINEERING LLC
US	74527333	1919529	05/17/1994	SPRAY-CURE	RAPID ENGINEERING

Schedule 2 to Patent and Trademark Security Agreement

52560921v.2

Country	Serial No.	<u>No.</u>	Registration Date	Mark	Current Assignee / Remarks
			09/19/1995		LLC

## **U.S.** Trademark Applications

N/A

# Non-U.S. Trademark Registrations

Country	Serial No.	Registration No.	Application/ Registration Date	<u>Mark</u>	Current Assignee / Remarks
CA	0759729	TMA 448095	07/19/1994 09/22/1995	BANANZA	RAPID ENGINEERING LLC
CA	1306507	TMA 744033	06/22/2006 07/24/2009	Rapid	RAPID ENGINEERING LLC
CA	1306565	TMA 744377	06/22/2006 07/30/2009	RAPID	RAPID ENGINEERING LLC
CA	1306569	TMA 744212	06/22/2006 07/29/2009		RAPID ENGINEERING LLC
CN	10750720	10750720	04/11/2012 04/14/2014	RAPID	RAPID ENGINEERING LLC
KR	5020080010651	4004098140000	5/27/2008 10/31/2008	<b>Rapid</b>	RAPID ENGINEERING, INC.

# Non-U.S. Trademark Applications

N/A

Schedule 2 to Patent and Trademark Security Agreement

52560921v.2

**RECORDED: 12/21/2018**